



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-17
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS3L60UF	7N6Y*Z67Q83U	A	ZA41	2018-09-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	50.00	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMC	4.3 - 3.75 - 1	2	flat	
Comment	Package: SMB Flat NEP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die	340
Lead	2.57	Soft solder	51360

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.57	Soft solder	51360
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.57	Soft solder	924739

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7N6Y*Z67Q83U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.349	mg	supplier	die	Silicon (Si)	7440-21-3		1.241	mg	919668	24820
				supplier	metallization	Aluminium (Al)	7429-90-5		0.060	mg	44464	1200
				supplier	passivation	Nickel (Ni)	7440-02-0		0.007	mg	5187	140
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	741	20
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1482	40
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	6670	180
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	741	20
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1482	40
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	7411	200
				supplier	polymer die coating	Durimide	Proprietary		0.016	mg	12154	320
Lead-frame & Clip	Copper & its alloys	24.213	mg	Supplier	alloy	Copper (Cu)	7440-50-8		24.182	mg	998720	483640
				Supplier	alloy	Iron (Fe)	7439-89-6		0.024	mg	991	480
				Supplier	alloy	Phosphorus (P)	12185-10-3		0.007	mg	289	140
Die Attach	Solder	2.777	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.070	mg	25207	1400
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.139	mg	50054	2780
				Supplier	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.568	mg	924739	51360
				Supplier	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.568	mg	924739	51360
Encapsulation	Other inorganic materials	20.789	mg	Supplier	mold compound	Silica , amorphous,fused	60676-86-0		17.249	mg	829718	344980
				Supplier	mold compound	Epoxy resin propietare,resin unknown	29690-82-2		2.795	mg	134446	55900
				Supplier	mold compound	Benzophenone teracarboxylic anhydride	2421-28-5		0.114	mg	5484	2280
				Supplier	mold compound	Silica, quartz	14808-60-7		0.517	mg	24869	10340
				Supplier	mold compound	Carbon black	1333-86-4		0.114	mg	5483	2280
Connections coating	Solder	0.872	mg	Supplier	solder alloy	Tin (Sn)	7440-31-5		0.872	mg	1000000	17440